

530 Rec'd PCT/PTO 24 JUN 2002

Received  
PCT



DOCKET NUMBER: 215207US0PCT/pmh

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:  
Toshi ORIKABE, et al.

: GROUP: 1755

SERIAL NUMBER: 09/926,370

: ATTENTION:  
Application Division  
Customer Corrections

FILED: DECEMBER 28, 2001

FOR: THERMOSETTING RESIN COMPOSITION AND FLEXIBLE CIRCUIT  
OVERCOATING MATERIAL COMPRISING THE SAME

REQUEST FOR CORRECTED OFFICIAL FILING RECEIPT

Assistant Commissioner for Patents  
Washington, D.C. 20231

RECEIVED  
JUL 23 2002  
TC 1700

Sir:

The Patent Office is requested to provide a corrected Official Filing Receipt for the attached. No fees are required. If you have any questions, please do not hesitate to contact us.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,  
MAIER & NEUSTADT, P.C.

Norman F. Oblon  
Attorney of Record  
Registration Number 24,618

Roland E. Martin  
Registration No. 48,082



**22850**

Tel. (703) 413-3000  
Fax. (703) 413-2220  
(OSMMN 10/98)

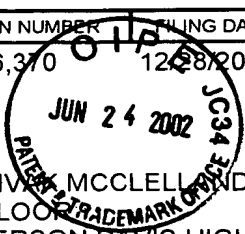


## UNITED STATES PATENT AND TRADEMARK OFFICE

COMMISSIONER FOR PATENTS  
UNITED STATES PATENT AND TRADEMARK OFFICE  
WASHINGTON, D.C. 20231  
www.uspto.gov

APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO.	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/926,370	12/28/2001	1755	1300	215207US0PCT		5	2

22850

OBLON SPIVAK MCCLELLAND MAIER & NEUSTADT PC  
FOURTH FLOOR  
1755 JEFFERSON DAVIS HIGHWAY  
ARLINGTON, VA 22202

CONFIRMATION NO. 9246

## FILING RECEIPT



\*OC000000008219968\*

Date Mailed: 06/05/2002

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

## Applicant(s)

Hiroshi Oriabe, Kanagawa, JAPAN;  
Hiroshi Sakamoto, Kanagawa, JAPAN;  
Tadahiko Yokota, Kanagawa, JAPAN;

## Domestic Priority data as claimed by applicant

THIS APPLICATION IS A 371 OF PCT/JP00/02646 04/21/2000 MAIER &amp; NEUSTADT, P.C.

## Foreign Applications

JAPAN 11/115081 04/22/1999

RECEIVED: 6-10-02

OBLON, SPIVAK, MCCLELLAND

MAIER &amp; NEUSTADT, P.C.

DOCKETING DEPT.

Initials/Date Docketed: HSA 6-11-02

Type of Resp(s):

Due Date(s):

Projected Publication Date: Not Applicable, filed prior to November 29, 2000

Non-Publication Request: No

Early Publication Request: No

RECEIVED

JUL 23 2002

TC 1700

## Title

Thermosetting resin composition and flexible circuit overcoating material comprising the same

## Preliminary Class

106

PLEASE NOTE THAT THE APPLICANTS' CITIES ARE INCORRECT. THEY SHOULD READ AS FOLLOWS:

1ST= HIROSHI ORIKABE, KANAGAWA-KEN, JAPAN  
2ND= HIROSHI SAKAMOTO, KANAGAWA-KEN, JAPAN  
3RD= TADAHIKO YOKOTA, KANAGAWA-KEN, JAPAN